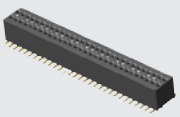
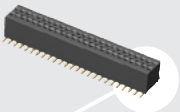
chanhvinh.com

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CLE–130–01–G–DV


CLE–108–01–G–DV


CLE–125–01–G–DV

(0.80 mm) .0315"

CLE SERIES

COST-EFFECTIVE MICRO SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLE

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au over 50 µ" (1.27 µm) Ni
Current Rating (CLE/FTE):
2.7 A per pin
(1 pin powered per row)
Operating Temp Range:
-55 °C to +125 °C
Contact Resistance:
15 mΩ
Insertion Depth:
Top Entry = (1.73 mm) .068" to (3.18 mm) .125" with (0.38 mm) .015" wipe, or pass-through
Bottom Entry = (3.23 mm) .127" minimum plus board thickness
Normal Force:
75 grams (0.73 N)
Max Cycles:
100 with 10 µ" (0.25 µm) Au
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (04-65)
(0.15 mm) .006" max (66-90)

RECOGNITIONS

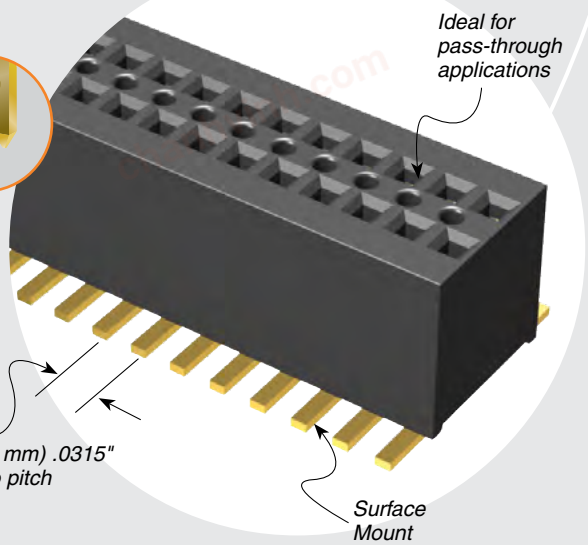
For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

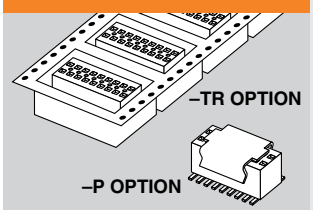
Note: Some lengths, styles and options are non-standard, non-returnable.

Mates with:
FTE, AW

TIGER BEAM™ CONTACT



OPTIONS



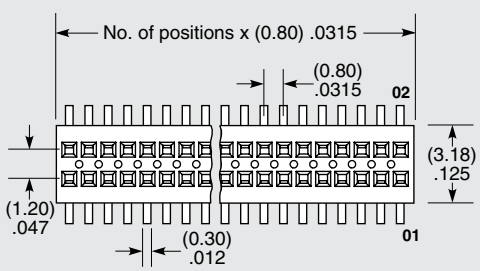
CLE	–	1	NO. PINS PER ROW	–	01	–	PLATING OPTION	–	DV	–	OPTIONS
			04 thru 90				–G = 10 µ" (0.25 µm) Gold				

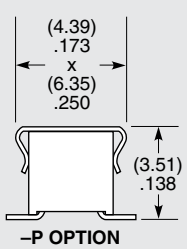
–A
= Alignment Pin (4 positions minimum) Metal or plastic at Samtec discretion.

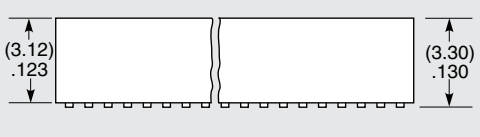
–K
= (3.50 mm) .138" DIA Polyimide film Pick & Place Pad (8 positions minimum)

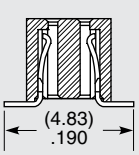
–P
= Metal Pick & Place Pad (8 positions minimum)

–TR
= Tape & Reel Packaging









Due to technical progress, all designs, specifications and components are subject to change without notice.